Features

- 7-Channel High Current Sink Drivers
- Supports up to 20V Output Pull-up Voltage
- Low Output VOL of 0.6V (Typical) with
- 100mA (Typ.) Current Sink per Channel at 3.3V Logic Input
- 140mA (Typ.) Current Sink per Channel at 5.0V Logic Input
- Compatible to 3.3V and 5.0V Micro-Controllers and Logic Interface
- Internal Free-wheeling Diodes for Inductive Kick-back Protection
- Input Pull-down Resistors Allows Tri-Stating the Input Driver
- Input RC-Snubber to Eliminate Spurious Operation in Noisy Environments
- ESD: 4kV HBM, 1kV CDM
- Available in 16-Pin DIP、SOP、QSOP and 16-Pin TSSOP packages

DIP-16

SOP-16

TSSOP-16

QSOP-16

Ordering Information

DEVICE	Package Type	MARKING	Packing	Packing Qty
ULN2003LVN	DIP-16	ULN2003LV	TUBE	1000pcs/box
ULN2003LVM/TR	SOP-16	ULN2003LV	REEL	2500pcs/Reel
ULN2003LVMT/TR	TSSOP-16	2003LV	REEL	2500pcs/Reel
ULN2003LVMS/TR	QSOP-16	2003LV	REEL	2500pcs/Reel

Description

The ULN2003LV are multi-channel sink drivers comprised of 7-channel output stages. The ULN2003LV sink driver features 7 low output impedance drivers that minimize on-chip power dissipation and an actual low power upgrade version for popular ULN2003A family in real applications. When driving a typical 12V relay coil, a ULN2003LV will dissipate 12 times lower power compared to ULN2003A.

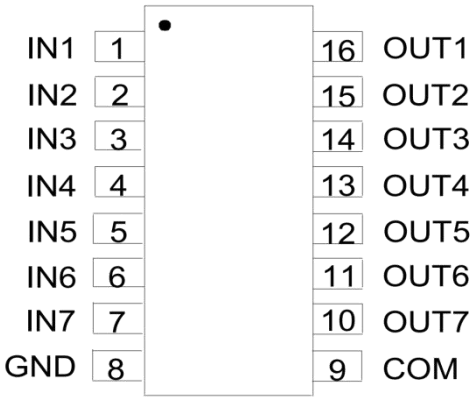
The ULN2003LV both support 3.3V to 5V CMOS logic input interface, thus making it compatible to a wide range of micro-controllers and other logic interfaces, and also feature an improved input interface that minimizes the input DC current drawn from the external drivers. The input RC snubber circuit integrated at ULN2003LV improves the performance in noisy operating conditions, and the internal pull-down resistor at input stage helps allow input logic to be tri-stated.

As shown in the Functional Diagram, each output of the ULN2003LV features an internal free-wheeling diode connected in a common-cathode configuration at the COM pin which provides flexibility of increasing current sink capability through combining several adjacent channels in parallel. Under typical conditions the ULN2003LV can support up to 1.0A of load current when all 7- channels are connected in parallel.

Applications

- Inputs Compatible with Popular Logic Types
- Relay Driver Applications
- Stepping Motor Applications
- Logic Level Shifter

Pin Assignments

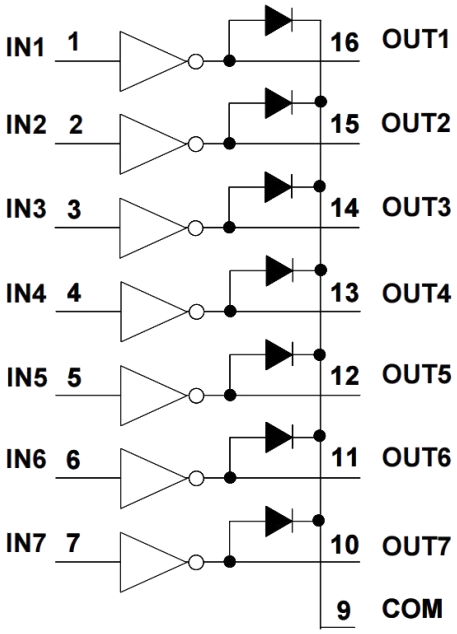


DIP-16/SOP-16/TSSOP-16/QSOP-16
(Top View)

Pin Descriptions

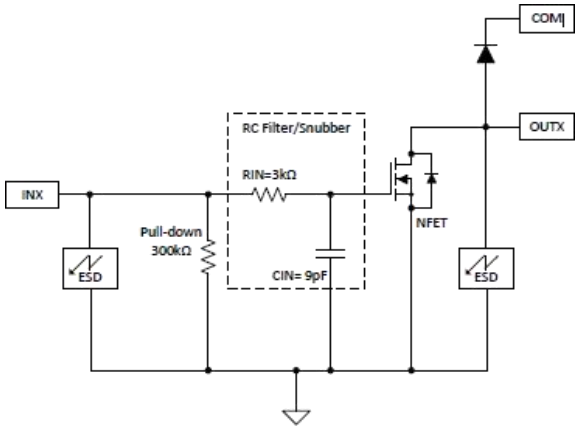
Pin Name	Pin Number	Description
IN1 ~ IN7	1~7	Logic Input Pins IN1 through IN7
GND	8	Ground Reference Pin
COM	9	Internal Free-Wheeling Diode Common Cathode Pin
OUT7 ~ OUT1	10~16	Channel Output Pins OUT7 through OUT1

Functional Diagram



ULN2003LV

Functional Block Diagram (Single Channel)



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter		Rating MIN	Rating MAX	Unit
V_{IN}	Pin2 IN1~IN7 to GND Voltage		-0.3	5.5	V
V_{OUT}	Pins OUT1~OUT7 to GND Voltage		-	20	V
V_{COM}	Pin COM to GND Voltage		-	20	V
I_{GND}	Max GND-Pin Continuous Current (+100°C <T_J < +125°C)		-	700	mA
	Max GND-Pin Continuous Current (TJ < +100°C)		-	1.0	A
P_D	Total Device Power Dissipation at TA = +85°C	16 Pin – SOP	TBD		W
		16 Pin – TSSOP	TBD		W
θ_{JA}	Thermal Resistance Junction-to-Ambient (Note 6)	16 Pin – SOP	TBD		°C/W
		16 Pin – TSSOP	TBD		
θ_{JC}	Thermal Resistance Junction-to-Case (Note 7)	16 Pin – SOP	TBD		°C/W
		16 Pin – TSSOP	TBD		
ESD	HBM		-	4	kV
	CDM		-	1	kV
T_J	Junction Temperature		-55	150	°C
T_{STG}	Storage Temperature		-55	150	°C
T_L	Lead Temperature (Soldering, 10 seconds)		-	260	°C

Notes:

4. Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only.
   Functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.
   Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
5. All voltage values are with respect to the emitter/substrate terminal E, unless otherwise noted.
6. Maximum power dissipation is a function of TJ(max), θJA, and TA. The maximum allowable power dissipation at any allowable ambient temperature is PD = (TJ(max) – TA)/θJA. Operating at the absolute maximum TJ of +150°C can affect reliability.
7. Maximum power dissipation is a function of TJ(max), θJC, and TA. The maximum allowable power dissipation at any allowable ambient temperature is PD = (TJ(max) – TC)/θJA. Operating at the absolute maximum TJ of +150°C can affect reliability.

Recommended Operating Conditions (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter		Min	TYP	Max	Unit
V_{OUT}	Channel Off-Stage Output Pull-Up Voltage		-	-	16	V
V_{COM}	COM Pin Voltage		-	-	16	V
$I_{OUT(ON)}$	Per Channel Continuous Sink Current	VINx = 3.3V	-	-	100(5)	mA
		VINx = 5.0V	-	-	140(5)	
T_J	Operating Junction Temperature (1)		-40	-	125	°C

Note(1) :Operating temperature range: -40°C to +125°C. This product is designed for industrial grade applications. For automotive grade versions compliant with AEC-Q100, please conduct internal screening per the standard or contact our sales team for availability.

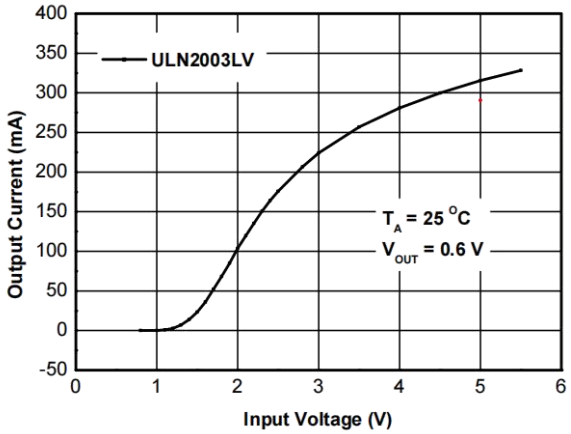
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Specified over the recommended junction temperature range T_J=-40°C to +125°C and over recommended operating conditions unless otherwise noted. Typical values are at T_J = +25°C.

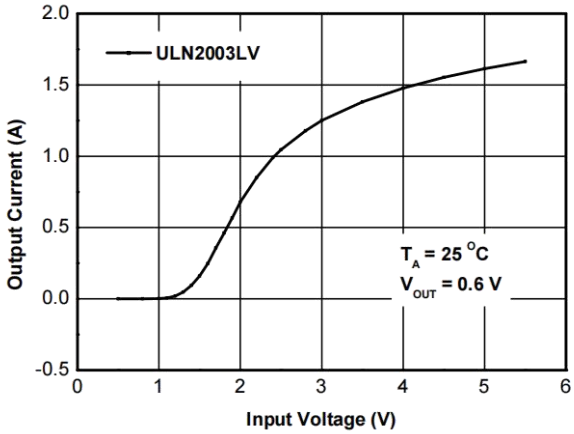
Parameter		Test conditions	Min	Typ.	Max	Unit
INPUTS IN1 THROUGH IN7 PARAMETERS						
$V_{I(on)}$	IN1~IN7 logic high input voltage	V_{CE} = 2V, I_C = 80mA	1.65	-	-	V
$V_{I(OFF)}$	IN1~IN7 logic low input voltage	I_C = 5μA	-	-	0.5	V
$I_{I(ON)}$	IN1~IN7 ON state input current	Vi=3.3V	-	12	25	uA
$I_{I(OFF)}$	IN1~IN7 OFF state input leakage	Vi=0V	-	-	250	nA
OUTPUTS OUT1 THROUGH OUT7 PARAMETERS						
$V_{OL(VCE-SAT)}$	OUT1~OUT7 low-level output voltage	V_{INX} = 3.3V, I_{OUTX} = 20mA	-	0.12	0.15	V
		V_{INX} = 3.3V, I_{OUTX} = 100mA	-	0.6	0.75	
		V_{INX} = 5.0V, I_{OUTX} = 20mA	-	0.09	0.11	
		V_{INX} = 5.0V, I_{OUTX} = 140mA	-	0.6	0.75	
$I_{OUT(ON)}$	OUT1~OUT7 ON-state continuous current at V_{OUTX} = 0.6V	V_{INX} = 3.3V, V_{OUTX} = 0.6V	80	100	-	mA
		V_{INX} = 5.0V, V_{OUTX} = 0.6V	95	140	-	
$I_{OUT(ON)}$	OUT1~OUT7 OFF-state leakage current	V_{INX} = 0V, V_{OUTX} = V_{COM} =16V	-	0.5	-	uA
SWITCHING PARAMETERS						
t_{PHL}	OUT1~OUT7 logic high propagation delay	V_{INX} = 3.3V, $V_{pull-up}$ = 12V, Rpull-up = 1kΩ	-	50	70	ns
t_{PLH}	OUT1~OUT7 logic low propagation delay	V_{INX} = 3.3V, $V_{pull-up}$ = 12V, $R_{pull-up}$ = 1kΩ	-	121	140	ns
$t_{CHANNEL}$	Channel to channel delay	Over recommended operating conditions and with same test conditions on channels.	-	15	50	ns
R_{PD}	IN1~IN7 input pull-down resistance	-	210k	300k	390k	Ω
ζ	IN1~IN7 input filter time constant	-	-	9	-	ns
C_{OUT}	OUT1~OUT7 output capacitance	V_{INX} = 3.3V, V_{OUTX} = 0.4V	-	15	-	pF
FREE-WHEELING DIODE PARAMETERS						
VF	Forward voltage drop	I_{F-peak} = 140mA, V_F = V_{OUT}x -V_{COM}	-	1.2	-	V
I_{F-peak}	Diode peak forward current	-	-	140	-	mA

Performance Characteristics

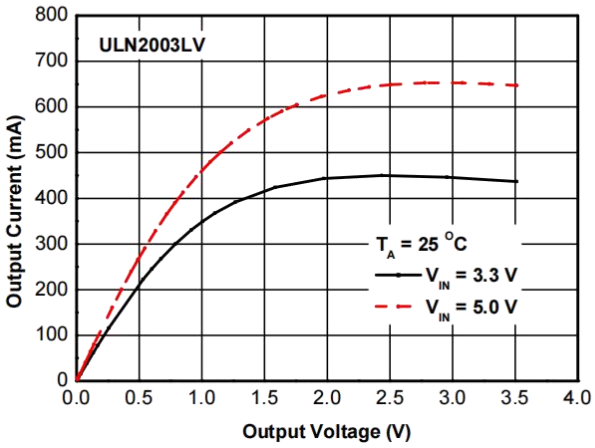
Output Current vs. Input Voltage (One Darlington)



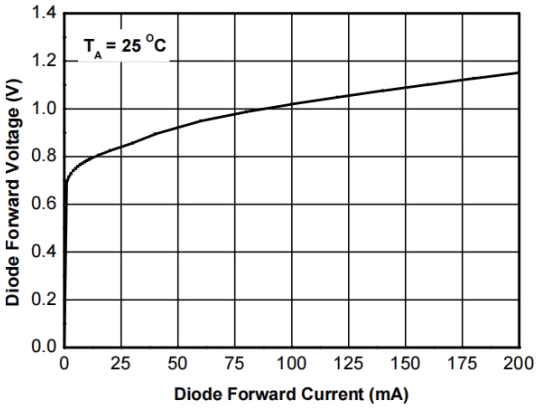
Output Current vs. Input Voltage (All Darlingtons in Parallel)



Output Current vs. Output Voltage

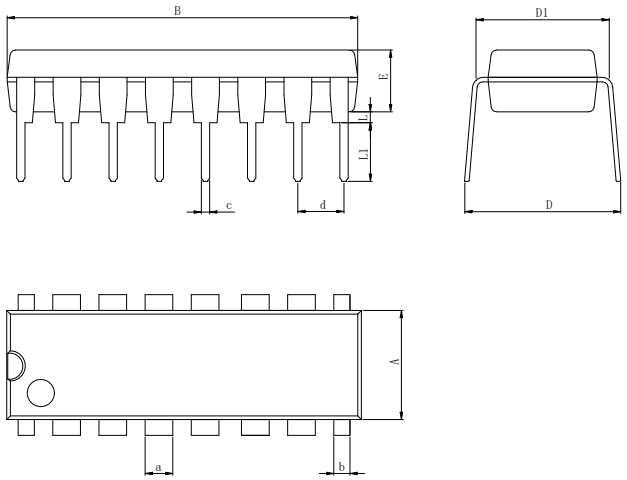


Diode Forward Voltage vs. Diode Forward Current



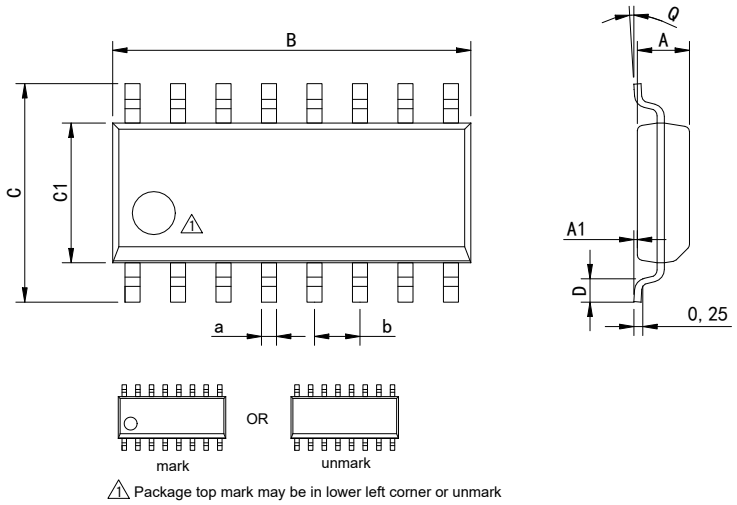
Physical Dimensions

DIP-16



Dimensions In Millimeters(DIP-16)											
Symbol:	A	B	D	D1	E	L	L1	a	b	c	d
Min:	6.10	18.94	8.10	7.42	3.10	0.50	3.00	1.50	0.85	0.40	2.54 BSC
Max:	6.68	19.56	10.9	7.82	3.55	0.70	3.60	1.55	0.90	0.50	

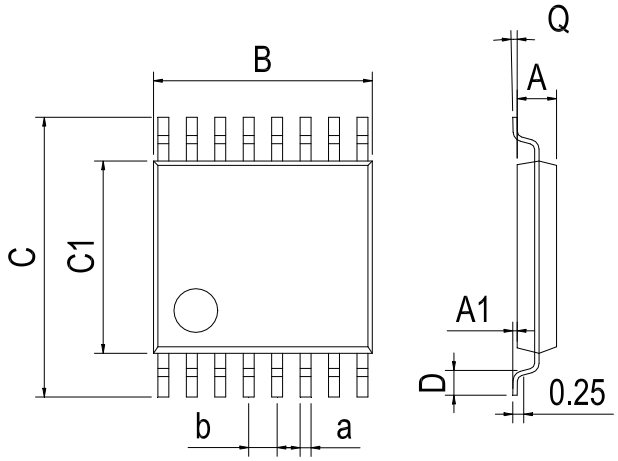
SOP-16



Dimensions In Millimeters(SOP-16)									
Symbol:	**A**	**A1**	**B**	**C**	**C1**	**D**	**Q**	**a**	**b**
Min:	1.35	0.05	9.80	5.80	3.80	0.40	0°	0.35	1.27 BSC
Max:	1.55	0.20	10.0	6.20	4.00	0.80	8°	0.45	

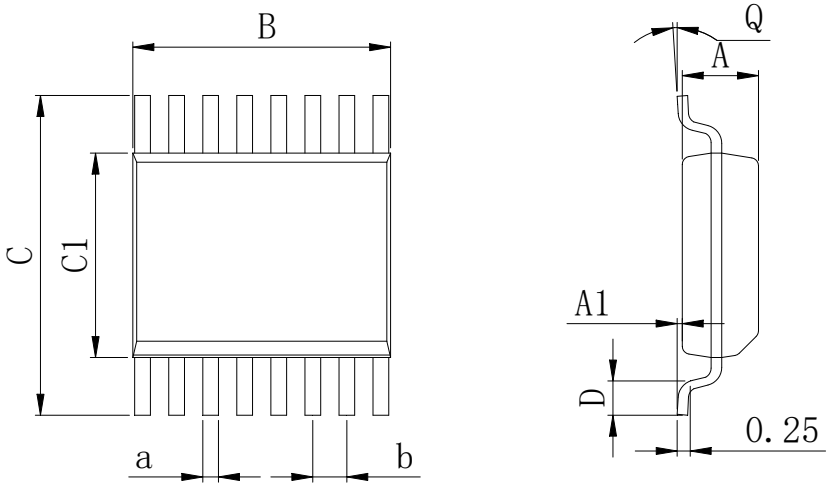
Physical Dimensions

TSSOP-16



Dimensions In Millimeters(TSSOP-16)									
Symbol:	A	A1	B	C	C1	D	Q	a	b
Min:	0.85	0.05	4.90	6.20	4.30	0.40	0°	0.20	0.65 BSC
Max:	0.95	0.20	5.10	6.60	4.50	0.80	8°	0.25	

QSOP-16



Dimensions In Millimeters(QSOP-16)									
Symbol:	**A**	**A1**	**B**	**C**	**C1**	**D**	**Q**	**a**	**b**
Min:	1.35	0.05	4.80	5.80	3.80	0.40	0°	0.20	0.635 BSC
Max:	1.55	0.20	5.10	6.20	4.00	0.80	8°	0.25	

Revision History

REVISION NUMBER	DATE	REVISION	PAGE
V1.0	2020-10	New	1-10
V1.1	2022-8	Modify the package dimension diagram TSSOP-16、Updated DIP-16 dimension	7、10
V1.2	2024-11	Update Lead Temperature	4
V1.3	2025-6	Add QSOP-16 package model	1
V1.4	2025-12	Update important statements、Update SOP-8 Dimension drawing	7、8

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